



Note:

1. Material:
  - 1.1 Housing: High temperature thermoplastic with g.f, UL94v-0
  - 1.2 Contact: copper alloy, t=0.20mm
  - 1.3 Shell: copper alloy, t=0.25mm
2. Specification:
  - 2.1 Current rating: 1 A Max.
  - 2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.
  - 2.3 Contact resistance: 50 mΩ Max.
  - 2.4 Insulation resistance: 100 MΩ Min.
  - 2.5 Total mating force: 3.57 Kgf Max.
  - 2.6 Total unmating force: 1.0 Kgf Min. 0.81~2.05 Kgf Min. after 10000 insertion/extraction cycles
  - 2.7 Temperature range: -30°C~80°C

RECOMMENDED PCB LAYOUT

HDC有限公司

设计 DRAW BY	杨帆	审核 DISCUSS BY		图名 DRAWING NO	MICRO USB B TYPE DIP	图号 SHEET NO	055	日期 DATE	2008.10.30
校对 DISCUSS BY		比例 SCALE	2:1	客户 VERSION		备注 REMARK	版次 REMARK	张号 SHEET	1/1